

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
5 June 2003 (05.06.2003)

PCT

(10) International Publication Number
WO 03/046950 A2

(51) International Patent Classification⁷: **H01L**

(21) International Application Number: PCT/US02/37860

(22) International Filing Date:
26 November 2002 (26.11.2002)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/333,689 27 November 2001 (27.11.2001) US

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(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZM, ZW.

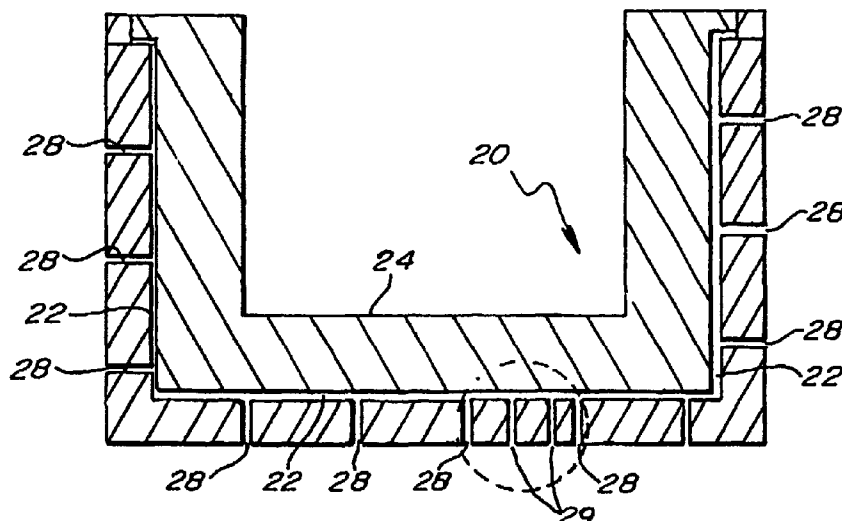
(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— without international search report and to be republished upon receipt of that report

[Continued on next page]

(54) Title: SEMICONDUCTOR COMPONENT HANDLING DEVICE HAVING A PERFORMANCE FILM



(57) Abstract: The present invention relates generally to a system and method for including a thin protective containment thermopolymer film, such as PEEK, in the molding process for handlers, transporters, carriers, trays and like devices utilized in the semiconductor processing industry. The thermoplastic film of predetermined size and shape is selectively placed along a shaping surface in a mold cavity for alignment with a desired target surface of a moldable material. The molding process causes a surface of the film to bond to a contact surface of the moldable material such that the film is permanently adhered to the moldable material. As a result, a compatible polymer film can be selectively bonded only to those target surfaces where performance characteristics such as abrasion resistance, heat resistance, chemical resistance, outgassing containment, rigidity enhancement, hardness, creep reduction, fluid absorption containment, and the like is needed.



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